HSSOP
Mount Pad Dimensions

β_2 L β_1 α H_E or H_D α β_1 L β_2

b_2 b
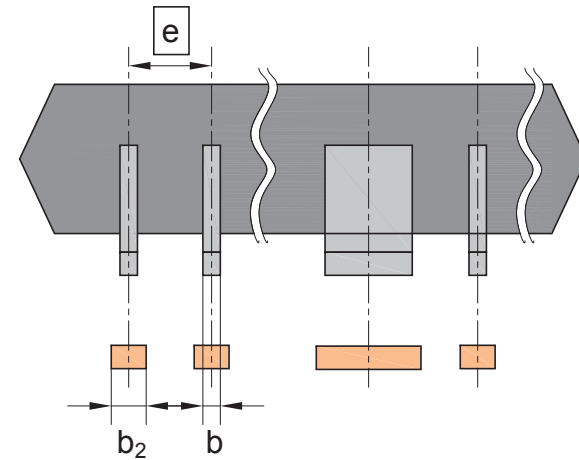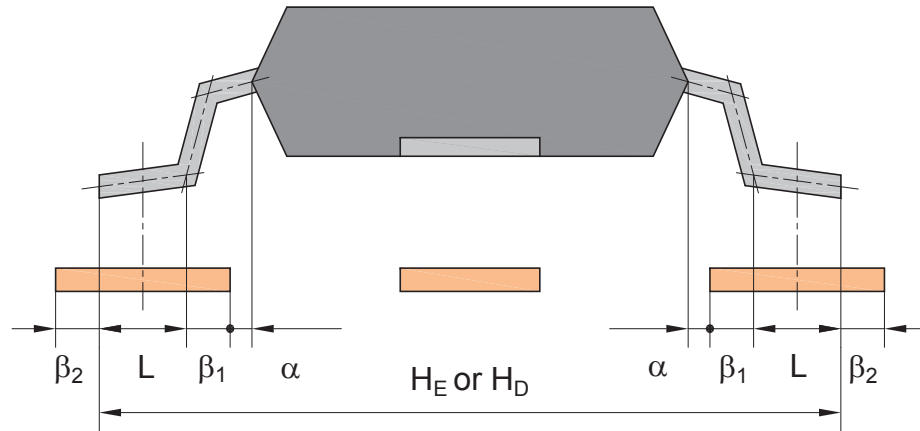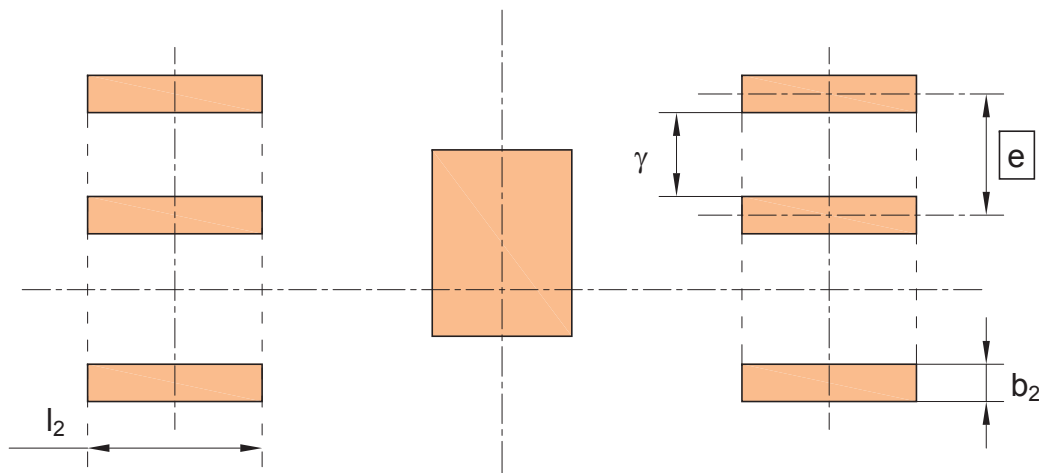
$l_2 = L + \beta_1 + \beta_2$

$b \leq b_2 \leq e - \gamma$

l_2 and b_2 can get by following formula and value e and b from package drawing figure and below parameter table.

- Dimension parameter

(Unit: mm)

e	0.80	0.65	0.50
α	0.10 to 0.30	←	←
β_1	0.20 to 0.50	←	0.20 to 0.40
β_2	0.20 to 0.40	←	←
γ	0.30	←	0.25

(Reference values based on the former EIAJ ED-7402 standard)

Note
- In case to use thermal pad, the size of thermalpad should be the same as the diepad.
- About the part of fins, these are designed according to b_2 leads. (assuming there are leads on both sides.)
  The pad between leads is made continuous.